

REMARKS


This is in response to the Official Action mailed June 18, 2001, in which Claims 1-41 were subjected to a Restriction Requirement. Applicants provisionally elect the invention of Group I. The Examiner indicated that Claims 1-4 and 22-24 are directed to Group I. Please note that Claim 1 was cancelled in a preliminary amendment filed November 30, 2000.

The Examiner indicates that the inventions of Group I and Group II are patentably distinct because the limitations recited in the claims directed to Group I have not been recited in the claims directed to Group II and vice-a-versa. However, Claim 5 (Group II), embraces the subject matter of Claim 2 (Group I). Claim 5 is directed to a method of injecting an encapsulant between a semiconductor chip and a substrate juxtaposed with the semiconductor chip. Claim 2 is directed to a method of providing a void-free underfill for a flip chip assembly. Both Claims 2 and 5 require a gap provided between a chip and a substrate. Pressure is applied to cause encapsulant to flow between the chip and the substrate. Claim 2 further requires electrical connections between contact pads on the semiconductor chip and the substrate and that the pressure applied causes the encapsulant to flow into the gap and around the electrical connections, among other requirements. However, Claims 2 and 5 are not mutually exclusive. Thus, Claims 5-10 and 25-30 should be included in Group I along with Claims 2-4 and 22-24.

If any fee is due in connection with this response,
the Examiner is authorized to charge our Deposit Account No.
12-1095 therefor.

Respectfully submitted,

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